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ATTY DOCKET NO. 353 USF	SERIAL NO. 10/017,077
APPLICANT Filson et al.	
FILING DATE December 14, 2001	GROUP 1724

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>l.c.</i>	AA	US - 3,658,697	04/25/72	Huether	210	18	
<i>l.c.</i>	AB	US - 3,870,033	03/11/75	Faylor et al.	126	360	
<i>l.c.</i>	AC	US - 3,873,581	03/25/75	Fitzpatrick et al.	260	370	
<i>l.c.</i>	AD	US - 3,928,192	12/23/75	Katzakian, Jr. et al.	210	30	
<i>l.c.</i>	AE	US - 4,303,704	12/01/81	Courduvelis et al.	427	345	
<i>l.c.</i>	AF	US - 5,045,213	09/03/91	Bowers	210	709	
<i>l.c.</i>	AG	US - 5,149,437	09/22/92	Wilkinson et al.	210	665	
<i>l.c.</i>	AH	US - 5,348,588	09/20/94	Winston	134	10	
<i>l.c.</i>	AI	US - 5,348,724	09/20/94	Hagimori et al.	423	531	
<i>l.c.</i>	AJ	US - 5,558,775	09/24/96	Busch, Jr.	210	638	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
<i>l.c.</i>	AK	0 761 603	12.03.1997	European	C02F	1/463	
<i>l.c.</i>	AL	WO 97/29048	14.08.1997	World	C02F	1/28	
<i>l.c.</i>	AM	06121978 Abstract	06.05.1994	Japan	C02F	1/28	
<i>l.c.</i>	AN	08024897 Abstract	30.01.1996	Japan	C02F	9/00	
<i>l.c.</i>	AO	08039054 Abstract	13.02.1996	Japan	C02F	1/28	
<i>l.c.</i>	AP	08141579 Abstract	04.06.1996	Japan	C02F	1/58	
<i>l.c.</i>	AQ	10111387 Abstract	28.04.1998	Japan	G21C	19/307	
<i>l.c.</i>	AR	09117763 Abstract	06.05.1997	Japan	C02F	1/44	
<i>l.c.</i>	AS	55062794 Abstract	12.05.1980	Japan			

OTHER DOCUMENTS

<i>l.c.</i>	AT	"A Circuit Board Manufacturer's Solution to Wastewater Treatment" Electronic Packaging and Production, vol. 35, no. 9 01.08.1995 pg 85	
Examiner	Date Considered	<i>I. Cinti's June 10, 2003</i>	

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with the next communication to applicant.